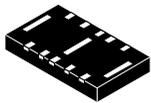


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

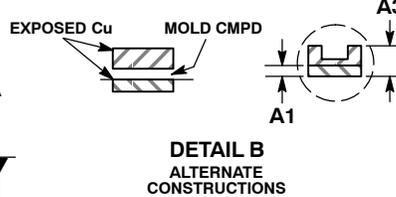
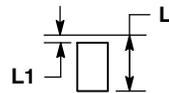
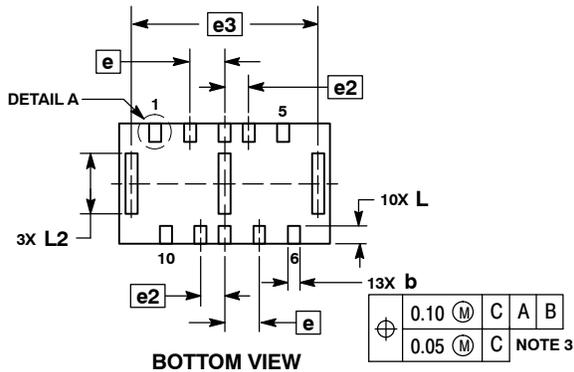
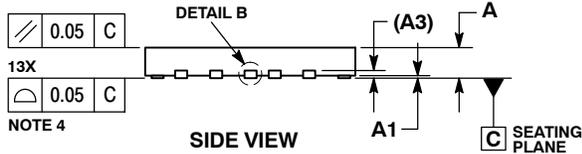
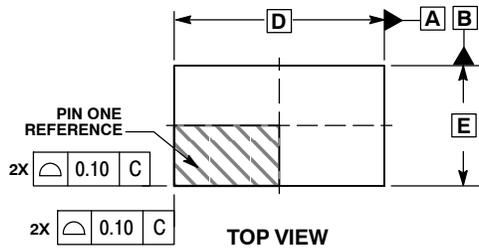
ON Semiconductor®



UDFN10 3.5x2, 0.575P  
CASE 506CU  
ISSUE O

DATE 05 NOV 2013

SCALE 4:1

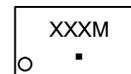


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127	REF
b	0.15	0.25
D	3.50 BSC	
E	2.00 BSC	
e	0.575 BSC	
e2	0.40 BSC	
e3	3.10 BSC	
L	0.25	0.35
L1	0.05	0.15
L2	0.95	1.05

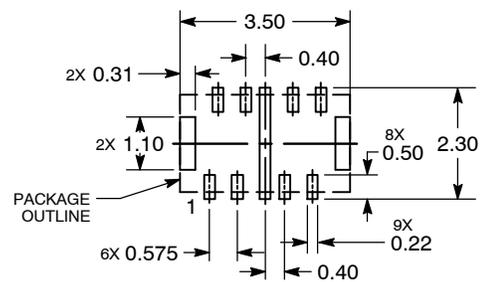
**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED MOUNTING FOOTPRINT**



DIMENSIONS: MILLIMETERS

<b>DOCUMENT NUMBER:</b>	98AON79787F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	UDFN10 3.5X2, 0.575P	<b>PAGE 1 OF 2</b>

